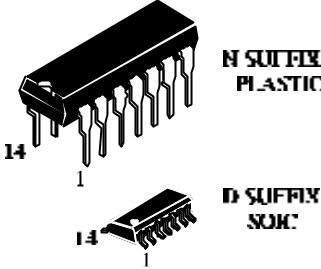


**SL74LV00****Quad 2-Input NAND Gate**

The SL74LV00 is low-voltage Si-gate CMOS device and is pin and function compatible with 74HC/HCT00A.

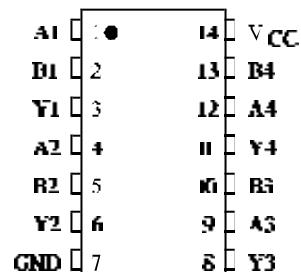
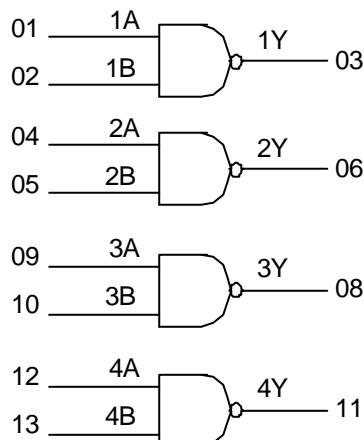
The SL74LV00 provides the 2-Input NAND function.

- Optimized for Low Voltage applications: 1.2 to 3.6 V
- Accepts TTL input levels between  $V_{CC} = 2.7$  V and  $V_{CC} = 3.6$  V
- Low Input Current

**ORDERING INFORMATION**

SL74LV00N Plastic

SL74LV00D SOIC

 $T_A = -40^\circ \text{ to } 125^\circ \text{ C}$  for all packages**PIN ASSIGNMENT****LOGIC DIAGRAM**

PIN 14 =  $V_{CC}$   
PIN 7 = GND

**FUNCTION TABLE**

Input		Output
A	B	$Y = \overline{A * B}$
L	L	H
L	H	H
H	L	H
H	H	L

H - high level  
L - low level

**MAXIMUM RATINGS\***

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC supply voltage (Referenced to GND)	-0.5 ÷ +5.0	V
I <sub>IK</sub> * <sup>1</sup>	DC input diode current	±20	mA
I <sub>OK</sub> * <sup>2</sup>	DC output diode current	±50	mA
I <sub>O</sub> * <sup>3</sup>	DC output source or sink current -bus driver outputs	±25	mA
I <sub>CC</sub>	DC V <sub>CC</sub> current for types with - bus driver outputs	±50	mA
I <sub>GND</sub>	DC GND current for types with - bus driver outputs	±50	mA
P <sub>D</sub>	Power dissipation per package, plastic DIP+ SOIC package+	750 500	mW
T <sub>tsg</sub>	Storage temperature	-65 ÷ +150	°C
T <sub>L</sub>	Lead temperature, 1.5 mm from Case for 10 seconds (Plastic DIP ), 0.3 mm (SOIC Package)	260	°C

\*Maximum Ratings are those values beyond which damage to the device may occur.

Functional operation should be restricted to the Recommended Operating Conditions.

+Derating - Plastic DIP: - 12 mW/°C from 70° to 125°C

SOIC Package: : - 8 mW/°C from 70° to 125°C

\*<sup>1</sup>: V<sub>I</sub> < -0.5 or V<sub>I</sub> > V<sub>CC</sub>+0.5V

\*<sup>2</sup>: V<sub>O</sub> < -0.5 or V<sub>O</sub> > V<sub>CC</sub>+0.5V

\*<sup>3</sup>: -0.5V < V<sub>O</sub> < V<sub>CC</sub>+0.5V

**RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit	
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	1.2	3.6	V	
V <sub>IN</sub> , V <sub>OUT</sub>	DC Input Voltage, Output Voltage (Referenced to GND)	0	V <sub>CC</sub>	V	
T <sub>A</sub>	Operating Temperature, All Package Types	-40	+125	°C	
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time	V <sub>CC</sub> =1.2 V V <sub>CC</sub> =2.0 V V <sub>CC</sub> =3.0 V V <sub>CC</sub> =3.6 V	0 0 0 0	1000 700 500 400	ns

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V<sub>IN</sub> and V<sub>OUT</sub> should be constrained to the range GND≤(V<sub>IN</sub> or V<sub>OUT</sub>)≤V<sub>CC</sub>.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V<sub>CC</sub>). Unused outputs must be left open.

**DC ELECTRICAL CHARACTERISTICS** (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V <sub>CC</sub> , V	Guaranteed Limit						Unit	
				25°C		-40°C ÷ 85°C		-40°C ÷ 125°C			
				min	max	min	max	min	max		
V <sub>IH</sub>	High-Level Input Voltage		1.2 2.0 3.0 3.6	0.9 1.4 2.1 2.5	- - - -	0.9 1.4 2.1 2.5	- - - -	0.9 1.4 2.1 2.5	- - - -	V	
V <sub>IL</sub>	Low -Level Input Voltage		1.2 2.0 3.0 3.6	- - - -	0.3 0.6 0.9 1.1	- - - -	0.3 0.6 0.9 1.1	- - - -	0.3 0.6 0.9 1.1	V	
V <sub>OH</sub>	High-Level Output Voltage	V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub> I <sub>O</sub> = -50 μA	1.2 2.0 3.0 3.6	1.1 1.92 2.92 3.52	- - - -	1.0 1.9 2.9 3.5	- - - -	1.0 1.9 2.9 3.5	- - - -	V	
		V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub> I <sub>O</sub> = -6.0 mA	3.0	2.48	-	2.34	-	2.20	-	V	
V <sub>OL</sub>	Low-Level Output Voltage	V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub> I <sub>O</sub> = 50 μA	1.2 2.0 3.0 3.6	- - - -	0.09 0.09 0.09 0.09	- - - -	0.1 0.1 0.1 0.1	- - - -	0.1 0.1 0.1 0.1	V	
		V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub> I <sub>O</sub> = 6.0 mA	3.0	-	0.33	-	0.4	-	0.5	V	
I <sub>IL</sub>	Low-Level Input Leakage Current	V <sub>I</sub> = 0 V	3.6	-	-0.1	-	-1.0	-	-1.0	μA	
I <sub>If</sub>	High-Level Input Leakage Current	V <sub>I</sub> = V <sub>CC</sub>	3.6	-	0.1	-	1.0	-	1.0	μA	
I <sub>NN</sub>	Quiescent Supply Current (per Package)	V <sub>I</sub> = 0 V or V <sub>CC</sub> I <sub>O</sub> = 0 μA	3.6	-	2.0	-	20	-	40	μA	

AC ELECTRICAL CHARACTERISTICS ( $C_L=50 \text{ pF}$ ,  $t_{LH} = t_{HL} = 6.0 \text{ ns}$ ,  $V_{IL}=0V$ ,  $V_{IH}=V_{CC}$ )

Symbol	Parameter	$V_{CC}$ V	Guaranteed Limit						Unit	
			25°C		-40°C ÷ 85°C		-40°C ÷ 125°C			
			min	max	min	max	min	max		
$t_{THL}, (t_{TLH})$	Output Transition Time, Any Output (Figure 1)	1.2	-	60	-	75	-	90	ns	
		2.0	-	16	-	20	-	24		
		*	-	10	-	13	-	15		
$t_{PHL}, (t_{PLH})$	Propagation Delay, Input A to Output Y (Figure 1)	1.2	-	135	-	405	-	405		
		2.0	-	23	-	28	-	34		
		*	-	14	-	18	-	21		
$C_I$	Input Capacitance	3.0	-	7.0	-	-	-	-	pF	
$C_{PD}$	Power Dissipation Capacitance (Per Inverter)	$\dot{Q}_A=25^\circ\text{N}$ , $V_i=0V \div V_{CC}$						pF		
		44								

\* -  $V_{CC}=(3.3 \pm 0.3) \text{ V}$ 

Used to determine the no-load dynamic power consumption:

$$P_D = C_{PD} V_{CC}^2 f_i + (C_L V_{CC}^2 f_o), f_i - \text{input frequency, } f_o - \text{output frequency (MHz)}$$

$$(C_L V_{CC}^2 f_o) - \text{sum of the outputs}$$

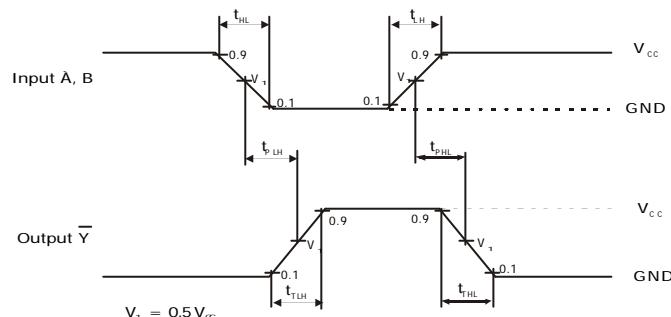
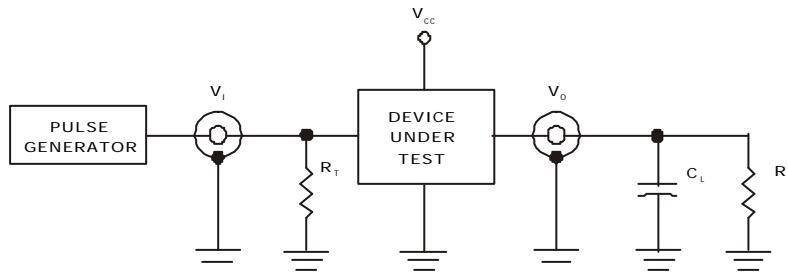


Figure 1. Switching Waveforms



Termination resistance  $R_T$  -  
should be equal to  $Z_{OUT}$  pulse  
generators

Figure 2. Test Circuit